

# 1.2V Drive Nch + Nch MOSFET

## UM6K33N

#### Structure

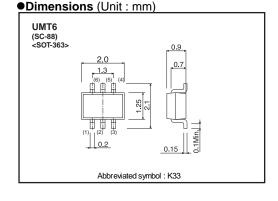
Silicon N-channel MOSFET

### ●Features

- 1) High speed switing.
- 2) Small package(UMT6).
- 3) Ultra low voltage drive(1.2V drive).

### Application

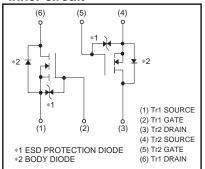
Switching



Packaging specifications

Туре	Package	Taping			
	Code	TN			
	Basic ordering unit (pieces)	3000			
UM6K33N		0			

## ●Inner circuit



● Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		$V_{DSS}$	50	V	
Gate-source voltage		$V_{GSS}$	±8	V	
Drain current	Continuous	I <sub>D</sub>	±200	mA	
	Pulsed	I <sub>DP</sub> *1	±800	mA	
Source current (Body Diode)	Continuous	l <sub>s</sub>	125	mA	
	Pulsed	I <sub>sp</sub> *1	800	mA	
Power dissipation		P <sub>D</sub> *2	150	mW / TOTAL	
		יט -	120	mW / ELEMENT	
Channel temperature		Tch	150	°C	
Range of storage temperature		Tstg	-55 to +150	°C	

<sup>\*1</sup> Pw $\leq$ 10 $\mu$ s, Duty cycle $\leq$ 1%

## ●Thermal resistance

Parameter	Symbol	Limits	Unit			
Channel to ambient	Rth (ch-a)	833	°C / W /TOTAL			
Charlie to ambient	ixiii (Cil-a)	1042	°C / W /ELEMENT			

<sup>\*</sup> Each terminal mounted on a recommended land.

<sup>\*2</sup> Each terminal mounted on a recommended land.

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## ●Electrical characteristics (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	1	-	±10	μA	$V_{GS}=\pm 8V, V_{DS}=0V$
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	50	-	-	٧	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	1	μA	$V_{DS}$ =50V, $V_{GS}$ =0V
Gate threshold voltage	V <sub>GS (th)</sub>	0.3	-	1.0	٧	$V_{DS}$ =10V, $I_{D}$ =1mA
		1	1.6	2.2		$I_D = 200 \text{mA}, V_{GS} = 4.5 \text{V}$
Chatia dualia accurac au atata		1	1.7	2.4		I <sub>D</sub> =200mA, V <sub>GS</sub> =2.5V
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	1	1.9	2.7	Ω	I <sub>D</sub> =100mA, V <sub>GS</sub> =1.8V
		1	2.0	4.0		I <sub>D</sub> =40mA, V <sub>GS</sub> =1.5V
		1	2.4	7.2		I <sub>D</sub> =20mA, V <sub>GS</sub> =1.2V
Forward transfer admittance	I Y <sub>fs</sub> I*	0.4	-	-	S	I <sub>D</sub> =200mA, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	1	25	-	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	1	6	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	3	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	4	-	ns	I <sub>D</sub> =100mA, V <sub>DD</sub> ≒ 30V
Rise time	t <sub>r</sub> *	1	6	-	ns	V <sub>GS</sub> =4.5V
Turn-off delay time	t <sub>d(off)</sub> *	1	15	-	ns	$R_L=300\Omega$
Fall time	t <sub>f</sub> *	-	55	-	ns	$R_G=10\Omega$

<sup>\*</sup>Pulsed

## ●Body diode characteristics (Source-Drain) (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

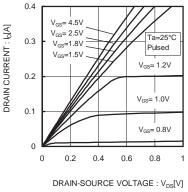
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	-	-	1.2	V	I <sub>s</sub> =200mA, V <sub>GS</sub> =0V

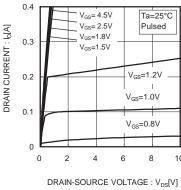
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<sup>\*</sup>Pulsed

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#### •Electrical characteristic curves





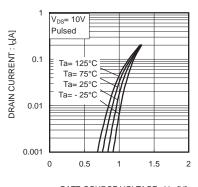


Fig.1 Typical Output Characteristics( I )

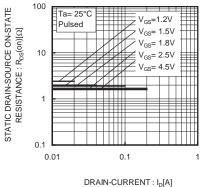
Fig.2 Typical Output Characteristics( II )

Ta=125°C

Ta=75°C

Ta=25°C

GATE-SOURCE VOLTAGE : V<sub>GS</sub>[V] Fig.3 Typical Transfer Characteristics



STATIC DRAIN-SOURCE ON-STATE  $RESISTANCE: R_{DS}(on)[\Omega]$ 0.1 0.01 0.1 DRAIN-CURRENT : I<sub>D</sub>[A]

100

10

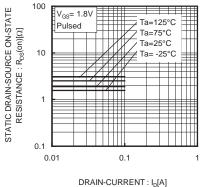
V<sub>GS</sub>= 4.5V

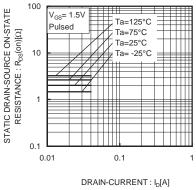
100 STATIC DRAIN-SOURCE ON-STATE  $V_{GS} = 2.5V$ Ta=125°C RESISTANCE :  $R_{DS}(on)[\Omega]$ Ta=75°C Ta=25°C 10 Ta= -25°C 0.1 0.01 0.1

Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

DRAIN-CURRENT : I<sub>2</sub>[A] Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )





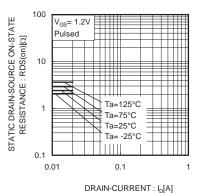


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current( IV )

Static Drain-Source On-State Resistance vs. Drain Current( V )

Fig.9 Static Drain-Source On-State Resistance vs. Drain Current( VI )

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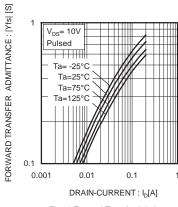


Fig.10 Forward Transfer Admittance vs. Drain Current

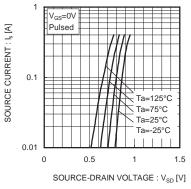


Fig.11 Reverse Drain Current vs. Sourse-Drain Voltage

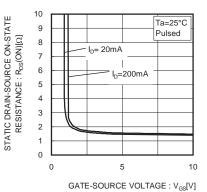
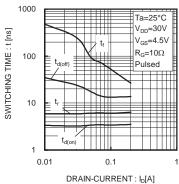
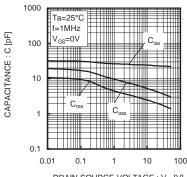


Fig.12 Static Drain-Source On-State Resistance vs. Gate Source Voltage







DRAIN-SOURCE VOLTAGE :  $V_{DS}[V]$ Fig.14 Typical Capacitance vs. Drain-Source Voltage

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## ● Measurement circuits

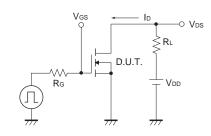


Fig.1-1 Switching time measurement circuit

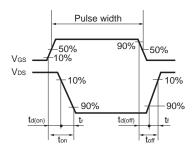


Fig.1-2 Switching waveforms

## ●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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